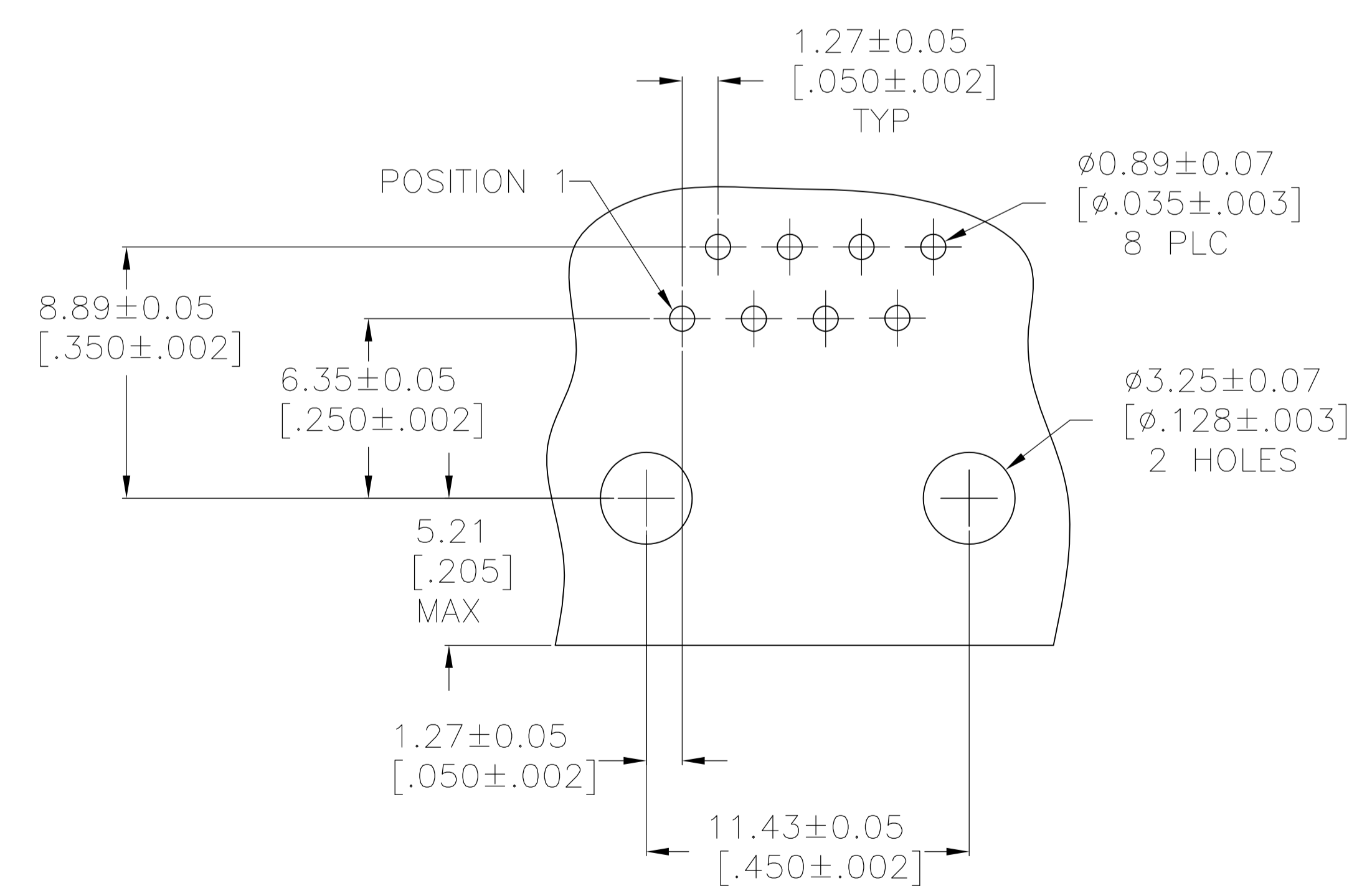


- MATERIAL: HOUSING - PBT POLYESTER, COLOR: BLACK  
TERMINAL - 0.35 [.014] THICK PHOSPHOR BRONZE PLATED WITH 1.27µm [.000050] THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 2.03µm [.000080] THICK MATTE TIN IN SOLDER AREA OVER 1.27µm [.000050] THICK NICKEL UNDERPLATE.
- CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.
- BULK PACKAGED IN A TRAY.



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT  
COMPONENT SIDE SHOWN

5555162-1  
PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN T. SPRINKLE/L.A. MAYER 22APR2005		STE TE Connectivity	
DIMENSIONS: mm [INCHES]		CHK J. WESTMAN 22APR2005		NAME	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD S. FLICKINGER 22APR2005		PRODUCT SPEC	
0 PLC ± -		APPLICATION SPEC		MODULAR JACK ASSEMBLY, 8 POSITION, LOW PROFILE, RIGHT ANGLE, WITH PANEL STOPS	
1 PLC ± -		114-2048		SIZE	
2 PLC ± -		A1		CAGE CODE	
3 PLC ± 0.13(.005)		00779		DRAWING NO	
4 PLC ± -		5555162		RESTRICTED TO	
ANGLES ± -		CUSTOMER DRAWING		SCALE	
MATERIAL SEE NOTE 1		FINISH SEE NOTE 1		SHEET 1 OF 1	
				REV D1	

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)